ERICSSON

PKD 4000E SI series DC/DC converters, Input 36-75 V, Output up to 20 A/50 W	EN/LZT 146 375 R2A October 2007

Key Features

- Low profile SMD within Quarter-brick size
  50.4 x 46.3 x 7.7 mm (1.98 x 1.82 x 0.303 in.)
- Low profile, max 8.0mm (0.315 in.)
- High efficiency, typ. 90 % at 3.3 Vout full load
- 1500 Vdc input to output isolation
- Meets isolation requirements equivalent to basic insulation according to IEC/EN/UL 60950
- More than 1.7 million hours MTBF

General Characteristics

- Suited for narrow board pitch applications
  (15 mm/0.6 in)
- Input under voltage shut-down
- Over temperature protection
- Soft start
- Output short-circuit protection
- Remote sense
- Remote control
- Output voltage adjust function
- Highly automated manufacturing ensures quality
- ISO 9001/14001 certified supplier

Safety Approvals

c UL us

Design for Environment

Pb

RoHS compatible

Meets requirements in high-temperature lead-free soldering processes.

Contents

General Information

Ordering Information

See Contents for individual product ordering numbers.

Option	Suffix	Ordering No.
SMD, lead-free surface finish	S	PKD 4218HE SI
SMD, leaded surface finish	SPB	PKD 4218HE SPBI

Reliability

The Mean Time Between Failure (MTBF) is calculated at full output power and an operating ambient temperature (T_A) of +40°C, which is a typical condition in Information and Communication Technology (ICT) equipment. Different methods could be used to calculate the predicted MTBF and failure rate which may give different results. Ericsson Power Modules currently uses Telcordia SR332.

Predicted MTBF for the series is:

- 1.79 million hours according to Telcordia SR332, issue 1, Black box technique.

Telcordia SR332 is a commonly used standard method intended for reliability calculations in ICT equipment. The parts count procedure used in this method was originally modelled on the methods from MIL-HDBK-217F, Reliability Predictions of Electronic Equipment. It assumes that no reliability data is available on the actual units and devices for which the predictions are to be made, i.e. all predictions are based on generic reliability parameters.

Compatibility with RoHS requirements

The products are compatible with the relevant clauses and requirements of the RoHS directive 2002/95/EC and have a maximum concentration value of 0.1% by weight in homogeneous materials for lead, mercury, hexavalent chromium, PBB and PBDE and of 0.01% by weight in homogeneous materials for cadmium.

Exemptions in the RoHS directive utilized in Ericsson Power Modules products include:

- Lead in high melting temperature type solder (used to solder the die in semiconductor packages)
- Lead in glass of electronics components and in electronic ceramic parts (e.g. fill material in chip resistors)
- Lead as an alloying element in copper alloy containing up to 4% lead by weight (used in connection pins made of Brass)

The exemption for lead in solder for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunication is only utilized in surface mount products intended for end-users' leaded SnPb Eutectic soldering processes. (See ordering information table).

Quality Statement

The products are designed and manufactured in an industrial environment where quality systems and methods like ISO 9000, 6σ (sigma), and SPC are intensively in use to boost the continuous improvements strategy. Infant mortality or early failures in the products are screened out and they are subjected to an ATE-based final test. Conservative design rules, design reviews and product qualifications, plus the high competence of an engaged work force, contribute to the high quality of our products.

Warranty

Warranty period and conditions are defined in Ericsson Power Modules General Terms and Conditions of Sale.

Limitation of Liability

Ericsson Power Modules does not make any other warranties, expressed or implied including any warranty of merchantability or fitness for a particular purpose (including, but not limited to, use in life support applications, where malfunctions of product can cause injury to a person's health or life).

Safety Specification

General information

Ericsson Power Modules DC/DC converters and DC/DC regulators are designed in accordance with safety standards IEC/EN/UL60950, *Safety of Information Technology Equipment*.

IEC/EN/UL60950 contains requirements to prevent injury or damage due to the following hazards:

- Electrical shock
- Energy hazards
- Fire
- Mechanical and heat hazards
- Radiation hazards
- Chemical hazards

On-board DC-DC converters and DC/DC regulators are defined as component power supplies. As components they cannot fully comply with the provisions of any Safety requirements without "Conditions of Acceptability". Clearance between conductors and between conductive parts of the component power supply and conductors on the board in the final product must meet the applicable Safety requirements. Certain conditions of acceptability apply for component power supplies with limited stand-off (see Mechanical Information for further information). It is the responsibility of the installer to ensure that the final product housing these components complies with the requirements of all applicable Safety standards and Directives for the final product.

Component power supplies for general use should comply with the requirements in IEC60950, EN60950 and UL60950 *"Safety of information technology equipment"*.
There are other more product related standards, e.g. IEEE802.3af "Ethernet LAN/MAN Data terminal equipment power", and ETS300132-2 "Power supply interface at the input to telecommunications equipment; part 2: DC", but all of these standards are based on IEC/EN/UL60950 with regards to safety.

Ericsson Power Modules DC/DC converters and DC/DC regulators are UL60950 recognized and certified in accordance with EN60950.

The flammability rating for all construction parts of the products meets requirements for V-0 class material according to IEC 60695-11-10.

The products should be installed in the end-use equipment, in accordance with the requirements of the ultimate application. Normally the output of the DC/DC converter is considered as SELV (Safety Extra Low Voltage) and the input source must be isolated by minimum Double or Reinforced Insulation from the primary circuit (AC mains) in accordance with IEC/EN/UL60950.

Isolated DC/DC converters

It is recommended that a slow blow fuse with a rating twice the maximum input current per selected product be used at the input of each DC/DC converter. If an input filter is used in the circuit the fuse should be placed in front of the input filter.
In the rare event of a component problem in the input filter or in the DC/DC converter that imposes a short circuit on the input source, this fuse will provide the following functions:

- Isolate the faulty DC/DC converter from the input power source so as not to affect the operation of other parts of the system.
- Protect the distribution wiring from excessive current and power loss thus preventing hazardous overheating.

The galvanic isolation is verified in an electric strength test.
The test voltage (V_{iso}) between input and output is
1500 Vdc or 2250 Vdc for 60 seconds (refer to product specification).
Leakage current is less than 1 μA at nominal input voltage.

24 V DC systems

The input voltage to the DC/DC converter is SELV (Safety Extra Low Voltage) and the output remains SELV under normal and abnormal operating conditions.

48 and 60 V DC systems

If the input voltage to the DC/DC converter is 75 Vdc or less, then the output remains SELV (Safety Extra Low Voltage) under normal and abnormal operating conditions.

Single fault testing in the input power supply circuit should be performed with the DC/DC converter connected to demonstrate that the input voltage does not exceed
75 Vdc.

If the input power source circuit is a DC power system, the source may be treated as a TNV2 circuit and testing has demonstrated compliance with SELV limits and isolation requirements equivalent to Basic Insulation in accordance with IEC/EN/UL60950.

Non-isolated DC/DC regulators

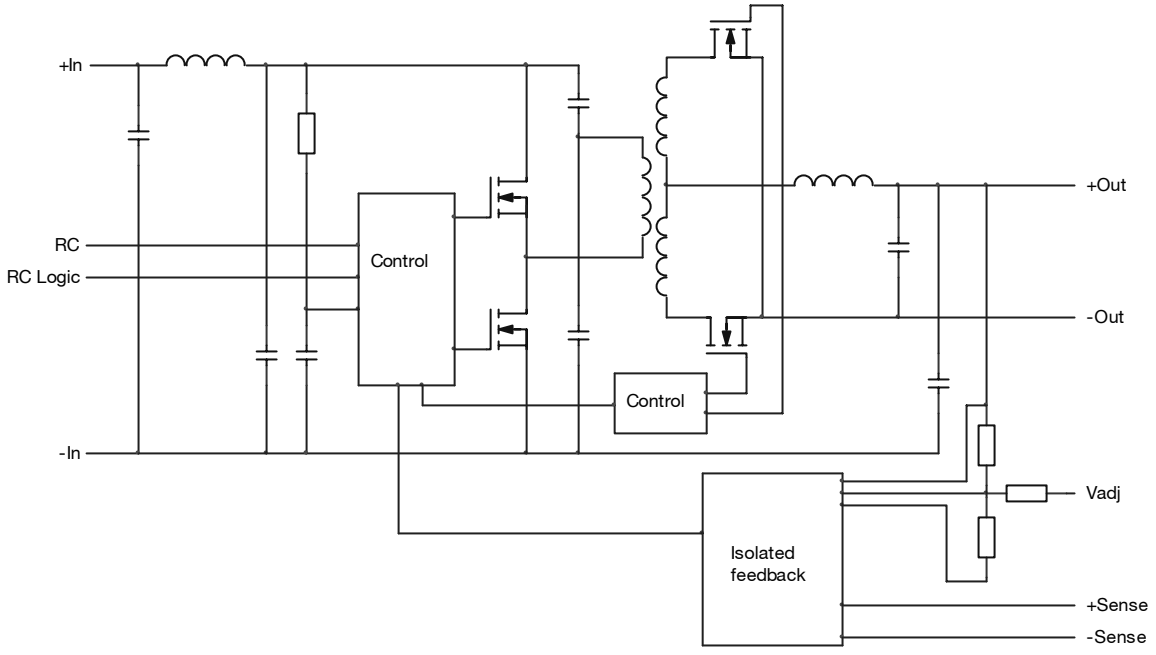
The input voltage to the DC/DC regulator is SELV (Safety Extra Low Voltage) and the output remains SELV under normal and abnormal operating conditions.

Absolute Maximum Ratings

Characteristics			min	typ	max	Unit
T_{ref}	Operating Temperature (see Thermal Consideration section)		-45		+110	°C
T_S	Storage temperature		-55		+125	°C
V_I	Input voltage		-0.5		+80	V
V_{iso}	Isolation voltage (input to output test voltage)		1500			V
V_{tr}	Input voltage transient (Tp 100 ms)				100	V
V_{RC}	Remote Control pin voltage (see Operating Information section)	Positive logic option	-0.5		9	V
		Negative logic option	-0.5		9	
V_{adj}	Adjust pin voltage (see Operating Information section)		-0.5		$2xV_{oi}$	V

Stress in excess of Absolute Maximum Ratings may cause permanent damage. Absolute Maximum Ratings, sometimes referred to as no destruction limits, are normally tested with one parameter at a time exceeding the limits of Output data or Electrical Characteristics. If exposed to stress above these limits, function and performance may degrade in an unspecified manner.

Fundamental Circuit Diagram



1.2 V/20 A Preliminary Electrical Specification — PKD 4218LE SI

T_{ref} = -25 to +90ºC, V_I = 36 to 75 V, sense pins connected to output pins unless otherwise specified under Conditions.
Typical values given at: T_{ref} = +25°C, V_I= 53 V, max I_O , unless otherwise specified under Conditions.

Characteristics		Conditions	min	typ	max	Unit
V_I	Input voltage range		36		75	V
V_{Ioff}	Turn-off input voltage	Decreasing input voltage	29			V
V_{Ion}	Turn-on input voltage	Increasing input voltage			36	V
C_I	Internal input capacitance			2.5		µF
P_O	Output power	Output voltage initial setting	0		24	W
SVR	Supply voltage rejection (ac)	f = 100 Hz sinewave, 1 Vp-p		66		dB
η	Efficiency	50 % of max I_O		85		%
		max I_O	80.5	84		
		50 % of max I_O , V_I = 48 V		85.5		
		max I_O , V_I = 48 V		84		
P_d	Power Dissipation	max I_O		4.6		W
P_{Ii}	Input idling power	I_O = 0 A, V_I = 53 V		1.1		W
P_{RC}	Input standby power	V_I = 53 V (turned off with RC)		0.7		W
f_s	Switching frequency	0-100 % of max I_O	162	180	198	kHz

V_{Oi}	Output voltage initial setting and accuracy	T_{ref} = +25°C, V_I = 53 V, I_O = 20 A	1.19	1.20	1.21	V
V_O	Output adjust range	See operating information	1.08		1.32	V
	Output voltage tolerance band	10-100% of max I_O	1.16		1.24	V
	Idling voltage	I_O = 0 A	1.16		1.24	V
	Line regulation	max I_O			5	mV
	Load regulation	V_I = 53 V, 1-100% of max I_O			5	mV
V_{tr}	Load transient voltage deviation	V_I = 53 V, Load step 25-75-25 % of max I_O, di/dt = 1 A/µs		±300		mV
t_{tr}	Load transient recovery time			60		µs
t_r	Ramp-up time (from 10–90 % of V_{Oi})	10-100% of max I_O		3		ms
t_s	Start-up time (from V_I connection to 90% of V_{Oi})			6		ms
t_f	Vin shutdown fall time (from V_I off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
t_{RC}	RC start-up time	max I_O		4		ms
	RC shutdown fall time (from RC off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
I_O	Output current		0		20	A
I_{lim}	Current limit threshold	T_{ref} < max T_{ref}		32		A
I_{sc}	Short circuit current	T_{ref} = 25ºC, V_O < 0.5 V			40	A
V_{Oac}	Output ripple & noise	See ripple & noise section, V_I = 53 V, I_O = 20 A		15	100	mVp-p

1.2 V/20 A Typical Characteristics

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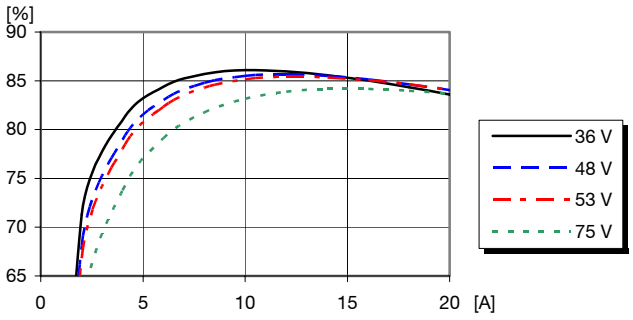
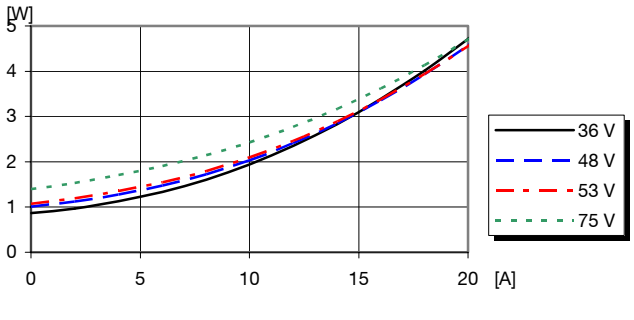
Efficiency



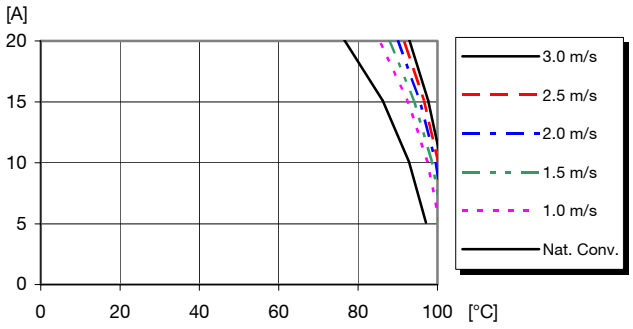
Efficiency vs. load current and input voltage at T_{ref} = +25°C

Power Dissipation



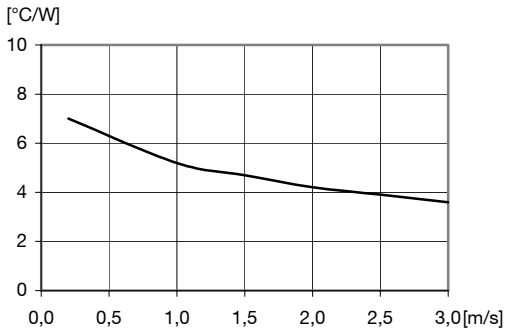
Dissipated power vs. load current and input voltage at T_{ref} = +25°C

Output Current Derating



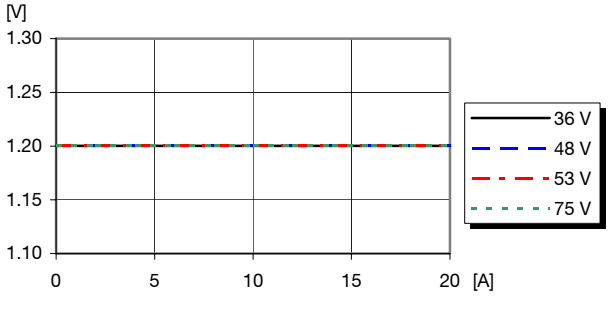
Available load current vs. ambient air temperature and airflow at V_I = 53 V. See Thermal Consideration section.

Thermal Resistance



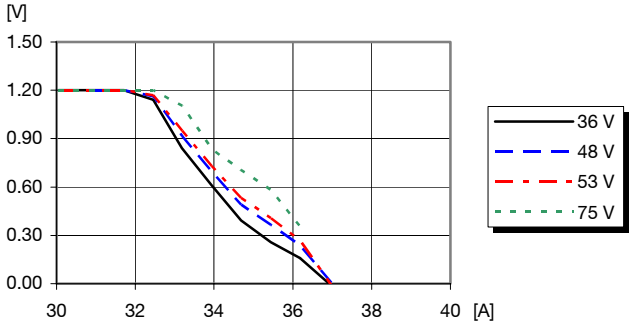
Thermal resistance vs. airspeed measured at the converter. Tested in wind tunnel with airflow and test conditions as per the Thermal consideration section.

Output Characteristics



Output voltage vs. load current at T_{ref} = +25°C

Current Limit Characteristics



Output voltage vs. load current at I_O > max I_O , T_{ref} = +25°C

1.2 V/20 A Typical Characteristics

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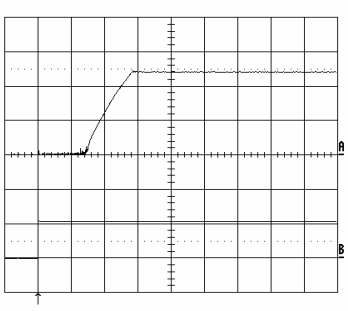
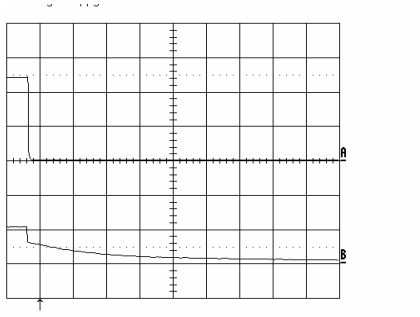
Start-up



Start-up enabled by connecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 20 A resistive load.

Top trace: output voltage (0.5 V/div).
Bottom trace: intput voltage (50 V/div).
Time scale: 2 ms/div.

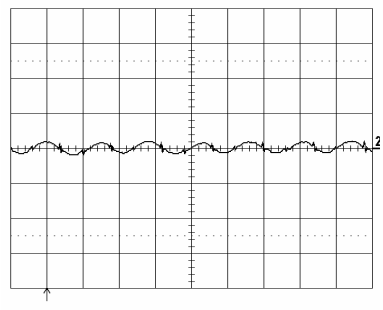
Shut-down



Shut-down enabled by disconnecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 20 A resistive load.

Top trace: output voltage (0.5 V/div).
Bottom trace: input voltage (50 V/div).
Time scale: 2 ms/div.

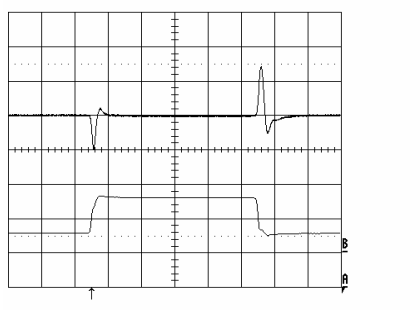
Output Ripple & Noise



Output voltage ripple at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 20 A resistive load.

Trace: output voltage (20mV/div).
Time scale: 2 µs/div.

Output Load Transient Response



Output voltage response to load current step-change (5-15-5 A}) at:
T_{ref} =+25°C, V_I = 53 V.

Top trace: output voltage (200mV/div).
Bottom trace: load current (10 A/div).
Time scale: 0.1 ms/div.

Output Voltage Adjust (see operating information)

Passive adjust
The resistor value for an adjusted output voltage is calculated by using the following equations:

Output Voltage Adjust Upwards, Increase:
R_{adj}= 6 / ((V_{out} / 1.2) - 1) - 40 kΩ

Example: Increase 4% =>V_{out} = 1.248 Vdc
6 / ((1.248 / 1.2) - 1) – 40 = 110 kΩ

Output Voltage Adjust Downwards, Decrease:
R_{adj}= ((15 x V_{out} – 7.2) / (1.2 – V_{out})) – 40 kΩ

Example: Decrease 2% =>V_{out} = 1.176 Vdc
((15 x 1.176 - 7.2) / (1.2 – 1.176)) – 40 = 395 kΩ

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T_{ref} = -25 to +90ºC, V_I = 36 to 75 V, sense pins connected to output pins unless otherwise specified under Conditions.
Typical values given at: T_{ref} = +25°C, V_I= 53 V, max I_O , unless otherwise specified under Conditions.

Characteristics		Conditions	min	typ	max	Unit
V_I	Input voltage range		36		75	V
V_{Ioff}	Turn-off input voltage	Decreasing input voltage	29			V
V_{Ion}	Turn-on input voltage	Increasing input voltage			36	V
C_I	Internal input capacitance			2.5		µF
P_O	Output power	Output voltage initial setting	0		21	W
SVR	Supply voltage rejection (ac)	f = 100 Hz sinewave, 1 Vp-p		65		dB
η	Efficiency	50 % of max I_O		84		%
		max I_O	84	86.5		
		50 % of max I_O , V_I = 48 V		84.5		
		max I_O , V_I = 48 V		86.5		
P_d	Power Dissipation	max I_O		3.3		W
P_{li}	Input idling power	I_O = 0 A, V_I = 53 V		1.3		W
P_{RC}	Input standby power	V_I = 53 V (turned off with RC)		0.7		W
f_s	Switching frequency	0-100 % of max I_O	162	180	198	kHz

V_{Oi}	Output voltage initial setting and accuracy	T_{ref} = +25°C, V_I = 53 V, I_O = 14 A	1.49	1.50	1.51	V
V_O	Output adjust range	See operating information	1.35		1.65	V
	Output voltage tolerance band	10-100% of max I_O	1.45		1.55	V
	Idling voltage	I_O = 0 A	1.45		1.55	V
	Line regulation	max I_O			5	mV
	Load regulation	V_I = 53 V, 0-100% of max I_O			5	mV
V_{tr}	Load transient voltage deviation	V_I = 53 V, Load step 25-75-25 % of max I_O, di/dt = 1 A/µs		±250		mV
t_{tr}	Load transient recovery time			60		µs
t_r	Ramp-up time (from 10–90 % of V_{Oi})	10-100% of max I_O		3		ms
t_s	Start-up time (from V_I connection to 90% of V_{Oi})			4		ms
t_f	Vin shutdown fall time (from V_I off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
t_{RC}	RC start-up time	max I_O		4		ms
	RC shutdown fall time (from RC off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
I_O	Output current		0		14	A
I_{lim}	Current limit threshold	T_{ref} < max T_{ref}		19		A
I_{sc}	Short circuit current	T_{ref} = 25ºC, V_O < 0.5 V			22	A
V_{Oac}	Output ripple & noise	See ripple & noise section, V_I = 53 V, I_O = 14 A		15	60	mVp-p

1.5 V/14 A Typical Characteristics

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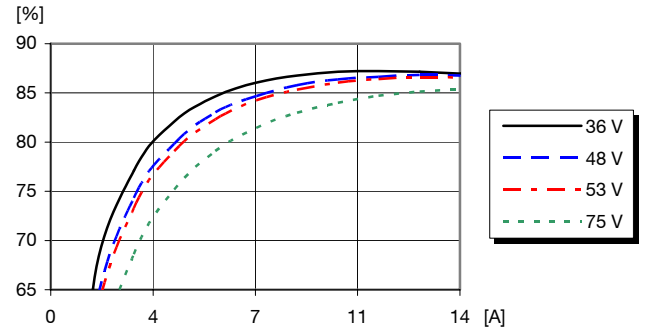
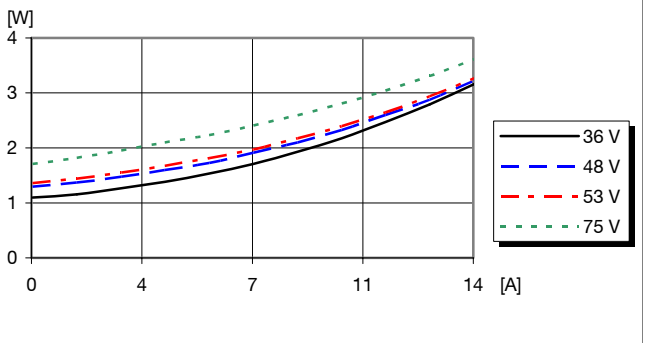
Efficiency



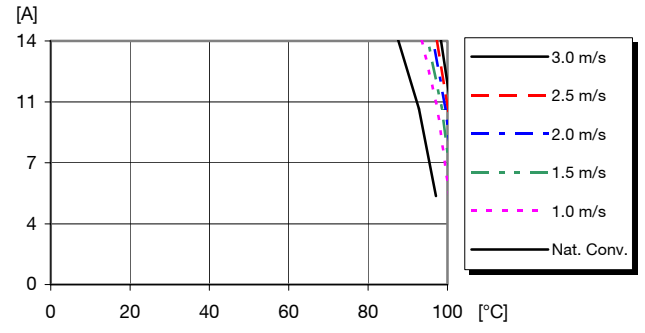
Efficiency vs. load current and input voltage at T_{ref} = +25°C

Power Dissipation



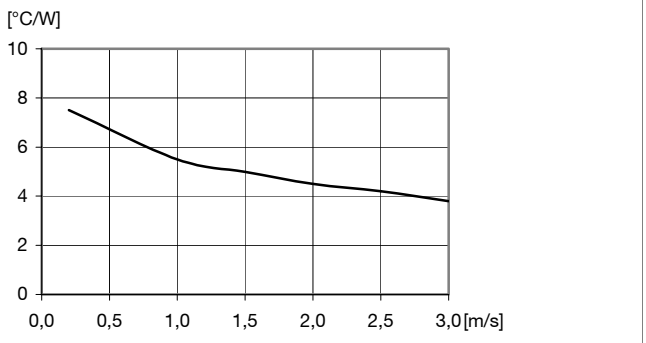
Dissipated power vs. load current and input voltage at T_{ref} = +25°C

Output Current Derating



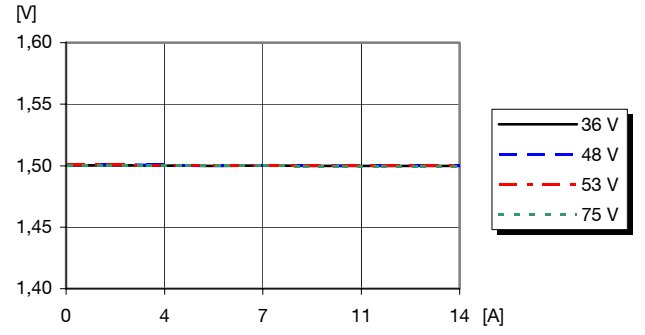
Available load current vs. ambient air temperature and airflow at V_I = 53 V. See Thermal Consideration section.

Thermal Resistance



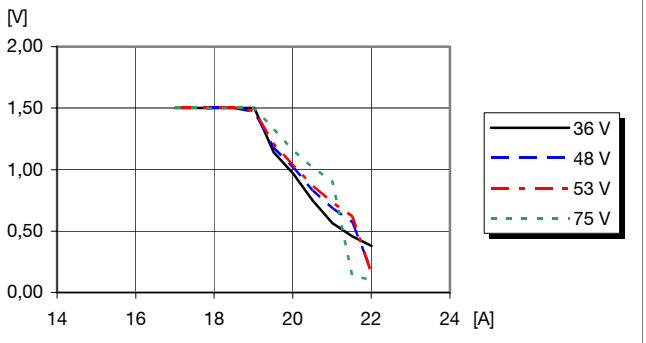
Thermal resistance vs. airspeed measured at the converter. Tested in wind tunnel with airflow and test conditions as per the Thermal consideration section.

Output Characteristics



Output voltage vs. load current at T_{ref} = +25°C

Current Limit Characteristics



Output voltage vs. load current at I_O > max I_O, T_{ref} = +25°C

1.5 V/14 A Typical Characteristics

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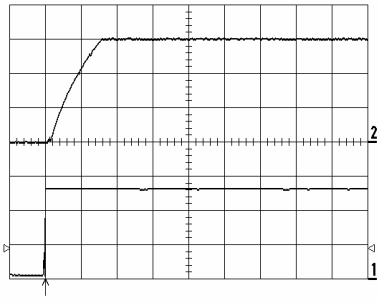
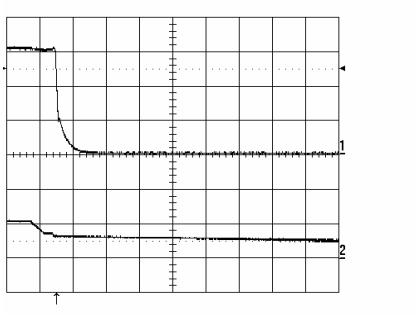
Start-up



Start-up enabled by connecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 14 A resistive load.

Top trace: output voltage (0.5 V/div).
Bottom trace: input voltage (20 V/div).
Time scale: 2 ms/div.

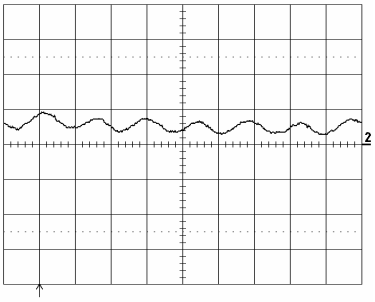
Shut-down



Shut-down enabled by disconnecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 14 A resistive load.

Top trace: output voltage (0.5 V/div).
Bottom trace: input voltage (50 V/div).
Time scale: 0.2 ms/div.

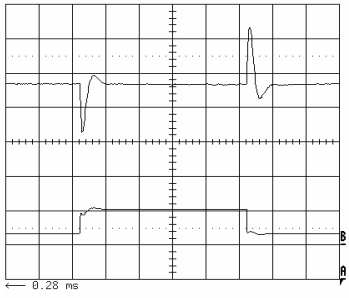
Output Ripple & Noise



Output voltage ripple at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 14 A resistive load.

Trace: output voltage (20mV/div).
Time scale: 2 µs/div.

Output Load Transient Response



Output voltage response to load current step-change (3.5-10.5-3.5 A}) at:
T_{ref} =+25°C, V_I = 53 V.

Top trace: output voltage (200mV/div).
Bottom trace: load current (10 A/div).
Time scale: 0.1 ms/div.

Output Voltage Adjust (see operating information)

Passive adjust
The resistor value for an adjusted output voltage is calculated by using the following equations:

Output Voltage Adjust Upwards, Increase:
R_{adj}= 6 / ((V_{out} / 1.5) - 1) - 40 kΩ

Example: Increase 4% =>V_{out} = 1.56 Vdc
6 / ((1.56 / 1.5) - 1) – 40 = 110 kΩ

Output Voltage Adjust Downwards, Decrease:
R_{adj}= ((15 x V_{out} – 9) / (1.5 – V_{out})) – 40 kΩ

Example: Decrease 2% =>V_{out} = 1.47 Vdc
((15 x 1.47 – 9) / (1.5 – 1.47)) – 40 = 395 kΩ

3.3 V/15 A Preliminary Electrical Specification — PKD 4510E SI

T_{ref} = -25 to +90°C, V_I = 36 to 75 V, sense pins connected to output pins unless otherwise specified under Conditions.
Typical values given at: T_{ref} = +25°C, V_I= 53 V, max I_O , unless otherwise specified under Conditions.

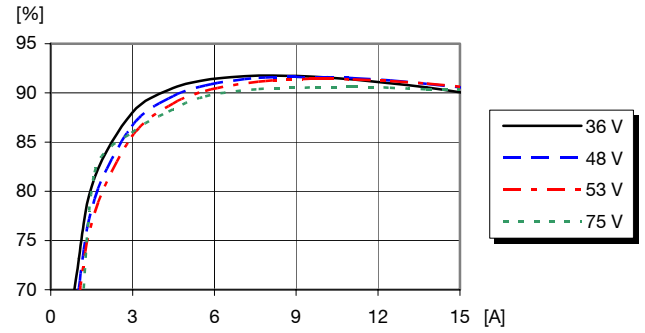
Characteristics		Conditions	min	typ	max	Unit
V_I	Input voltage range		36		75	V
V_{Ioff}	Turn-off input voltage	Decreasing input voltage	29			V
V_{Ion}	Turn-on input voltage	Increasing input voltage			36	V
C_I	Internal input capacitance			2.5		µF
P_O	Output power	Output voltage initial setting	0		50	W
SVR	Supply voltage rejection (ac)	f = 100 Hz sinewave, 1 Vp-p		71		dB
η	Efficiency	50 % of max I_O		91		%
		max I_O	88	90.5		
		50 % of max I_O , V_I = 48 V		91.5		
		max I_O , V_I = 48 V		90.5		
P_d	Power Dissipation	max I_O		5.2		W
P_{Ii}	Input idling power	I_O = 0 A, V_I = 53 V		1.4		W
P_{RC}	Input standby power	V_I = 53 V (turned off with RC)		0.7		W
f_s	Switching frequency	0-100 % of max I_O	162	180	198	kHz

V_{Oi}	Output voltage initial setting and accuracy	T_{ref} = +25°C, V_I = 53 V, I_O = 15 A	3.28	3.30	3.32	V
V_O	Output adjust range	See operating information	2.97		3.63	V
	Output voltage tolerance band	10-100% of max I_O	3.25		3.35	V
	Idling voltage	I_O = 0 A	3.25		3.35	V
	Line regulation	max I_O			5	mV
	Load regulation	V_I = 53 V, 0-100% of max I_O			5	mV
V_{tr}	Load transient voltage deviation	V_I = 53 V, Load step 25-75-25 % of max I_O, di/dt = 1 A/µs		±300		mV
t_{tr}	Load transient recovery time			60		µs
t_r	Ramp-up time (from 10–90 % of V_{Oi})	10-100% of max I_O		3		ms
t_s	Start-up time (from V_I connection to 90% of V_{Oi})			4		ms
t_f	Vin shutdown fall time (from V_I off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
t_{RC}	RC start-up time	max I_O		4		ms
	RC shutdown fall time (from RC off to 10% of V_O)	max I_O		0.5		ms
		I_O = 0 A		10		s
I_O	Output current		0		15	A
I_{lim}	Current limit threshold	T_{ref} < max T_{ref}		20		A
I_{sc}	Short circuit current	T_{ref} = 25°C, V_O < 0.5 V			25	A
V_{Oac}	Output ripple & noise	See ripple & noise section, V_I = 53 V, I_O = 20 A		20	100	mVp-p

3.3 V/15 A Typical Characteristics

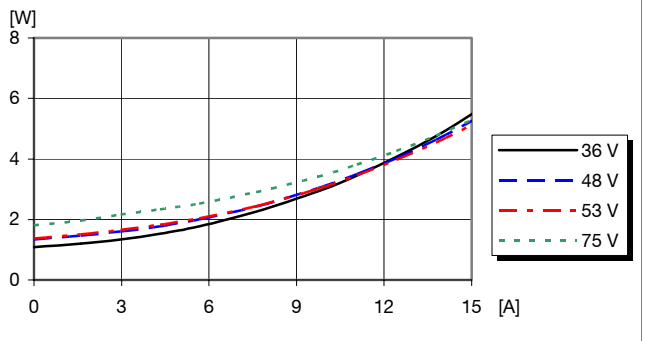
PKD 4510E SI

Efficiency



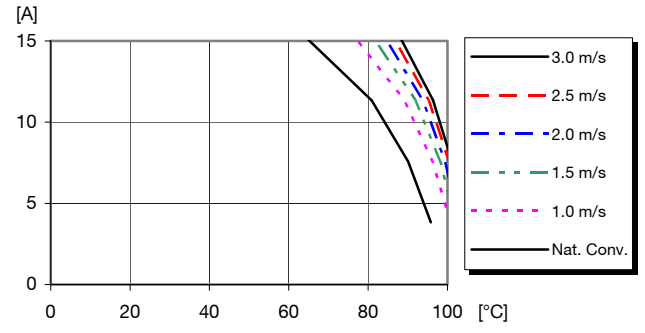
Efficiency vs. load current and input voltage at T_{ref} = +25°C

Power Dissipation



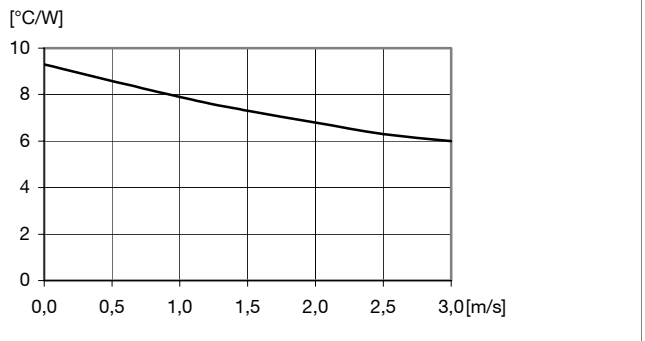
Dissipated power vs. load current and input voltage at T_{ref} = +25°C

Output Current Derating



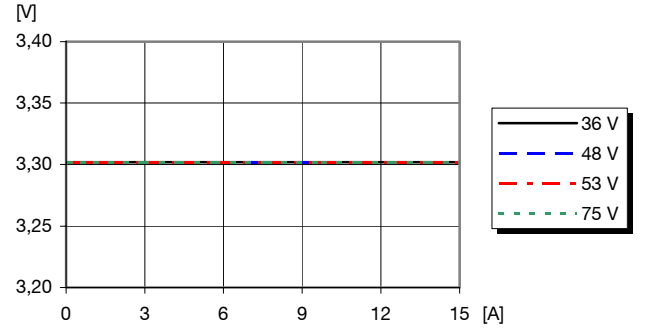
Available load current vs. ambient air temperature and airflow at V_I = 53 V. See Thermal Consideration section.

Thermal Resistance



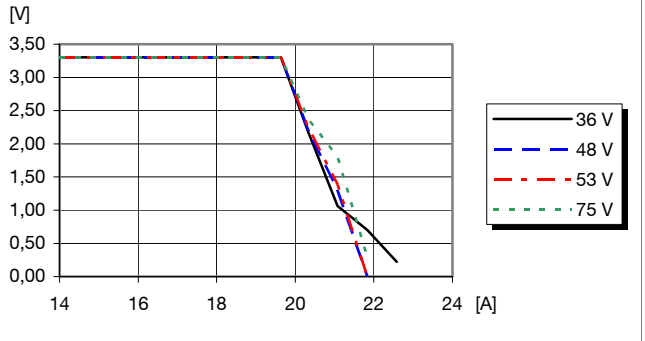
Thermal resistance vs. airspeed measured at the converter. Tested in wind tunnel with airflow and test conditions as per the Thermal consideration section.

Output Characteristics



Output voltage vs. load current at T_{ref} = +25°C

Current Limit Characteristics

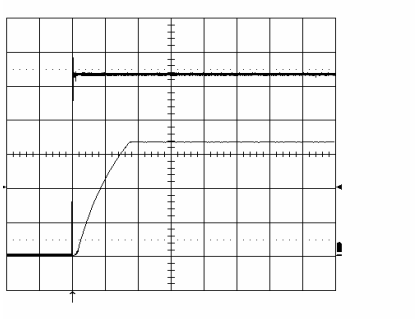


Output voltage vs. load current at I_O > max I_O , T_{ref} = +25°C

3.3 V/15 A Typical Characteristics

PKD 4510E SI

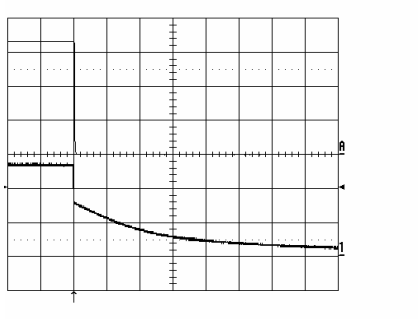
Start-up



Start-up enabled by connecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 15 A resistive load.

Top trace: intput voltage (10 V/div).
Bottom trace: output voltage (1 V/div).
Time scale: 2 ms/div.

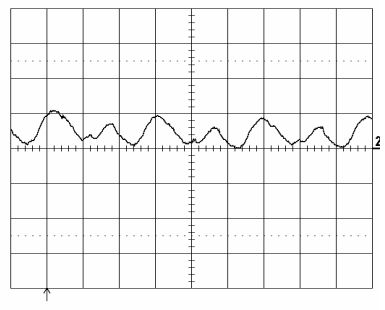
Shut-down



Shut-down enabled by disconnecting V_I at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 15 A resistive load.

Top trace: output voltage (1 V/div).
Bottom trace: input voltage (20 V/div).
Time scale: 2 ms/div.

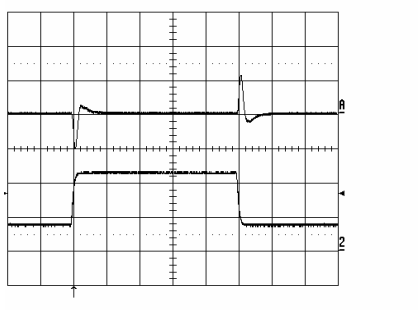
Output Ripple & Noise



Output voltage ripple at:
T_{ref} = +25°C, V_I = 53 V,
I_O = 15 A resistive load.

Trace: output voltage (20mV/div).
Time scale: 2 µs/div.

Output Load Transient Response



Output voltage response to load current step-change (3.75-11.25-3.75 A}) at:
T_{ref} =+25°C, V_I = 53 V.

Top trace: output voltage (200mV/div).
Bottom trace: load current (5 A/div).
Time scale: 0.1 ms/div.

Output Voltage Adjust (see operating information)

Passive adjust
The resistor value for an adjusted output voltage is calculated by using the following equations:

Output Voltage Adjust Upwards, Increase:
R_{adj}= 6 / ((V_{out} / 3.3) - 1) - 40 kΩ

Example: Increase 4% =>V_{out} = 3.432 Vdc
6 / ((3.432 / 3.3) - 1) – 40 = 110 kΩ

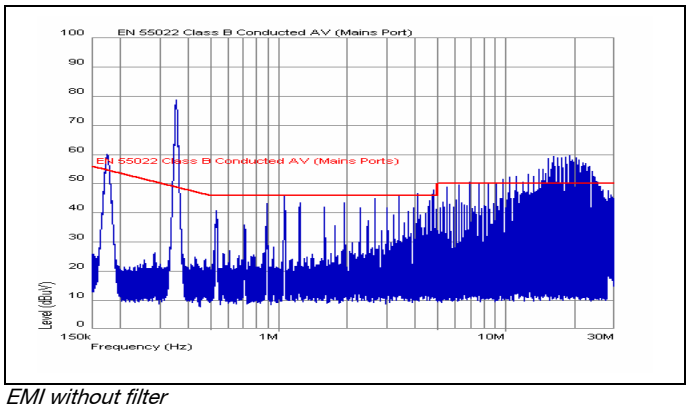
Output Voltage Adjust Downwards, Decrease:
R_{adj}= ((15 x V_{out} – 19.8) / (3.3 – V_{out})) – 40 kΩ

Example: Decrease 2% =>V_{out} = 3.234 Vdc
((15 x 3.234 – 19.8) / (3.3 – 3.234)) – 40 = 395 kΩ

EMC Specification

Conducted EMI measured according to EN55022, CISPR 22 and FCC part 15J (see test set-up). See Design Note 009 for further information. The fundamental switching frequency is 180 kHz for PKD4510E SI @ V_I = 53 V, max I_O.

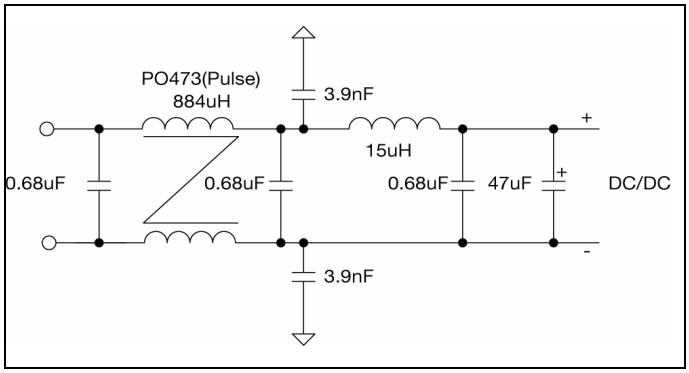
Conducted EMI Input terminal value (typ)

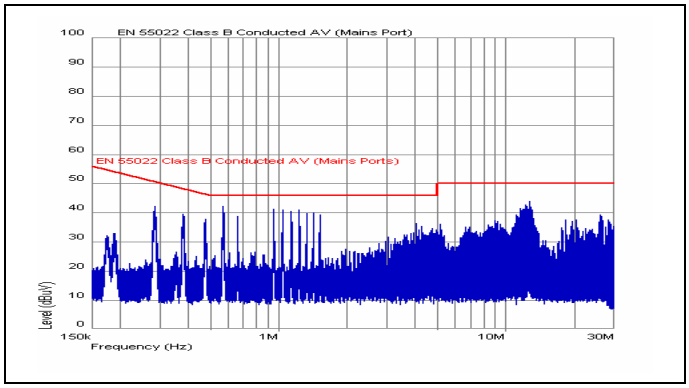


EMI without filter

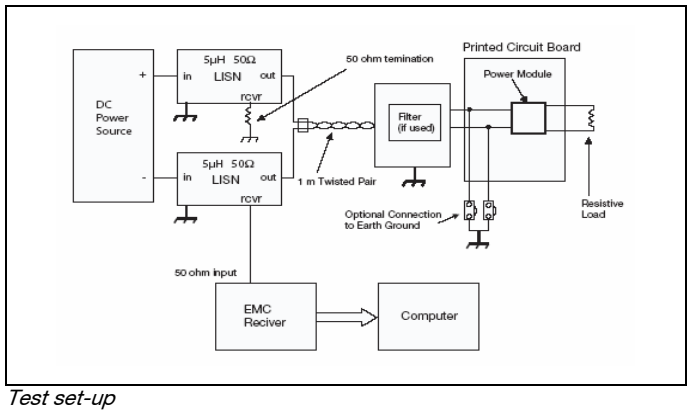
External filter (class B)

Required external input filter in order to meet class B in EN 55022, CISPR 22 and FCC part 15J.





EMI with filter



Test set-up

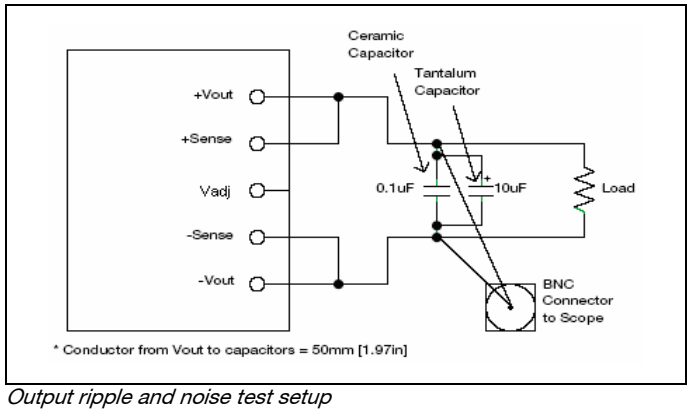
Layout recommendation

The radiated EMI performance of the DC/DC converter will depend on the PCB layout and ground layer design.
It is also important to consider the stand-off of the DC/DC converter.
If a ground layer is used, it should be connected to the output of the DC/DC converter and the equipment ground or chassis.

A ground layer will increase the stray capacitance in the PCB and improve the high frequency EMC performance.

Output ripple and noise

Output ripple and noise measured according to figure below. See Design Note 022 for detailed information.



Output ripple and noise test setup

Operating information

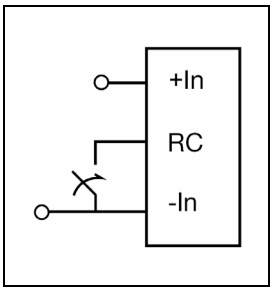
Input Voltage

The input voltage range 36 to 75 Vdc meets the requirements of the European Telecom Standard ETS 300 132-2 for normal input voltage range in –48 and –60 Vdc systems, -40.5 to -57.0 V and –50.0 to -72 V respectively.
At input voltages exceeding 75 V, the power loss will be higher than at normal input voltage and T_{ref} must be limited to absolute max +110°C. The absolute maximum continuous input voltage is 80 Vdc.

Turn-off Input Voltage

The DC/DC converters monitor the input voltage and will turn on and turn off at predetermined levels.
The minimum hysteresis between turn on and turn off input voltage is 2V.

Remote Control (RC)



The products are fitted with a remote control function referenced to the primary negative input connection (- In), with negative and positive logic options available.
The RC function allows the converter to be turned on/off by an external device like a semiconductor or mechanical switch.

The maximum required sink current is 1 mA. When the RC pin is left open, the voltage generated on the RC pin is 3.5 – 6.0 V.
The default option is “positive logic” remote control, which only requires that RC logic (pin 6) is left open. The converter will turn on when the input voltage is applied with the RC pin open. Turn off is achieved by connecting the RC pin to the - In. To ensure safe turn off the voltage difference between RC pin and the - In pin shall be less than 1V. The converter will restart automatically when this connection is opened.
The second option is “negative logic” remote control, which requires that RC logic (pin 6) is connected to –In (pin 3). The converter will be off until the RC pin is connected to the – In. To turn on the converter the voltage between RC pin and – In should be less than 1 V. To turn off the converter the RC pin should be left open, or connected to a voltage higher than 4V referenced to – In. In situations were it is desired to have the converter to power up automatically without the need for control signals or a switch, the RC pin can be wired directly to – In.

Input and Output Impedance

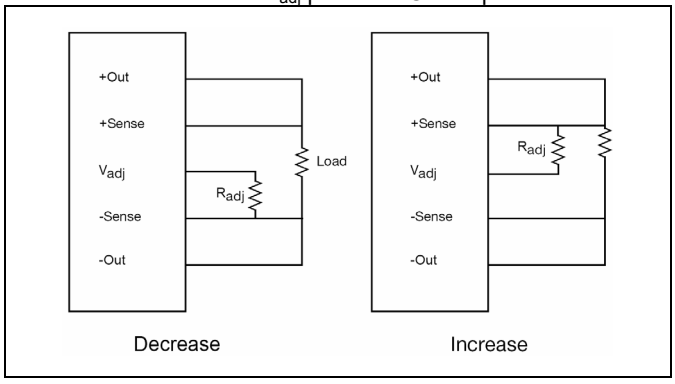
The impedance of both the input source and the load will interact with the impedance of the DC/DC converter. It is important that the input source has low characteristic impedance. The converters are designed for stable operation without external capacitors connected to the input or output. The performance in some applications can be enhanced by addition of external capacitance as described under External Decoupling Capacitors. If the input voltage source contains significant inductance, the addition of a 100 µF capacitor across the input of the converter will ensure stable operation. The capacitor is not required when powering the DC/DC converter from an input source with an inductance below 10 µH.

External Decoupling Capacitors

When powering loads with significant dynamic current requirements, the voltage regulation at the point of load can be improved by addition of decoupling capacitors at the load. The most effective technique is to locate low ESR ceramic and electrolytic capacitors as close to the load as possible, using several parallel capacitors to lower the effective ESR. The ceramic capacitors will handle high-frequency dynamic load changes while the electrolytic capacitors are used to handle low frequency dynamic load changes. Ceramic capacitors will also reduce any high frequency noise at the load.
It is equally important to use low resistance and low inductance PCB layouts and cabling.
External decoupling capacitors will become part of the control loop of the DC/DC converter and may affect the stability margins. As a “rule of thumb”, 100 µF/A of output current can be added without any additional analysis. The ESR of the capacitors is a very important parameter. Power Modules guarantee stable operation with a verified ESR value of >10 mΩ across the output connections.
For further information please contact your local Ericsson Power Modules representative.

Output Voltage Adjust (V_{adj})

The DC/DC converters have an Output Voltage Adjust pin (V_{adj}). This pin can be used to adjust the output voltage above or below Output voltage initial setting.
At increased output voltages the maximum power rating of the converter remains the same, and the max output current must be decreased correspondingly.
To increase the voltage the resistor should be connected between the V_{adj} pin and -Sense pin. The resistor value of the Output voltage adjust function is according to information given under the Output section for the respective product.
To decrease the output voltage, the resistor should be connected between the V_{adj} pin and +Sense pin.



Operating information continued

Parallel Operation

Two converters may be paralleled for redundancy if the total power is equal or less than P_O max. It is not recommended to parallel the converters without using external current sharing circuits.

{See Design Note 006 for detailed information.}

Remote Sense

The DC/DC converters have remote sense that can be used to compensate for voltage drops between the output and the point of load. The sense traces should be located close to the PCB ground layer to reduce noise susceptibility. The remote sense circuitry will compensate for up to 10% voltage drop between output pins and the point of load.

If the remote sense is not needed +Sense should be connected to +Out and -Sense should be connected to -Out.

Over Temperature Protection (OTP)

The converters are protected from thermal overload by an internal over temperature shutdown circuit.
When T_{ref} as defined in thermal consideration section exceeds 180°C the converter will shut down. The DC/DC converter will make continuous attempts to start up (non-latching mode) and resume normal operation automatically when the temperature has dropped >30°C below the temperature threshold.

Over Voltage Protection (OVP)

In the event of an overvoltage condition due to malfunction in the voltage monotoring circuits, the converter's PWM controller will automatically dictate minimum duty-cycle thus reducing the output voltage to a minimum.

Over Current Protection (OCP)

The converters include current limiting circuitry for protection at continuous overload.
The output voltage will decrease towards zero for output currents in excess of max output current (max I_O). The converter will resume normal operation after removal of the overload. The load distribution should be designed for the maximum output short circuit current specified.

Thermal Consideration

General

The converters are designed to operate in different thermal environments and sufficient cooling must be provided to ensure reliable operation.
Cooling is achieved mainly by conduction, from the pins to the host board, and convection, which is dependant on the airflow across the converter. Increased airflow enhances the cooling of the converter.

The Output Current Derating graph found in the Output section for each model provides the available output current vs. ambient air temperature and air velocity at V_{in} = 53 V.

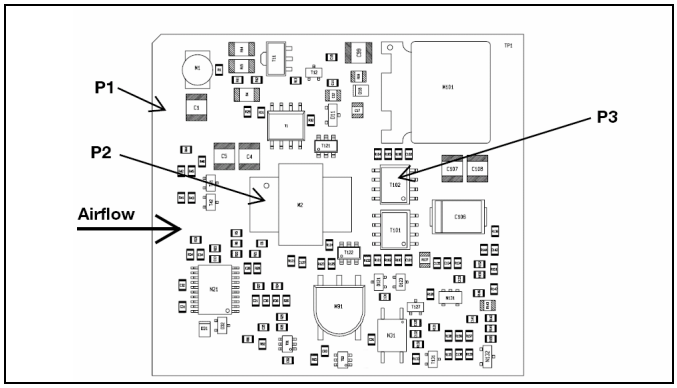
The DC/DC converter is tested on a 254 x 254 mm, 35 µm (1 oz), 8-layer test board mounted vertically in a wind tunnel with a cross-section of 305 x 305 mm.

Proper cooling of the DC/DC converter can be verified by measuring the temperature at positions P1, P2 and P3. The temperature at these positions should not exceed the max values provided in the table below.

Note that the max value is the absolute maximum rating (non destruction) and that the electrical Output data is guaranteed up to T_{ref} +90°C.

See Design Note 019 for further information.

Position	Device	Designation	max value
P_1	Case (topside)	T_{ref}	110° C
P_2	Transformer	T_{core}	110° C
P_3	Mosfet	$T_{surface}$	130° C



Definition of reference temperature (T_{ref})

The reference temperature is used to monitor the temperature limits of the product. Temperatures above maximum T_{ref} are not allowed and may cause degradation or permanent damage to the product. T_{ref} is also used to define the temperature range for normal operating conditions.

T_{ref} is defined by the design and used to guarantee safety margins, proper operation and high reliability of the module.

Ambient Temperature Calculation

By using the thermal resistance the maximum allowed ambient temperature can be calculated.

1. The power loss is calculated by using the formula ((1/η) - 1) × output power = power losses (Pd).
η = efficiency of converter. E.g 83.5 % = 0.835

2. Find the thermal resistance (Rth) in the Thermal Resistance graph found in the Output section for each model.
Calculate the temperature increase (ΔT).
ΔT = Rth x Pd

3. Max allowed ambient temperature is:
Max Tref - ΔT.

E.g PKD 4218LE SI at 1m/s:

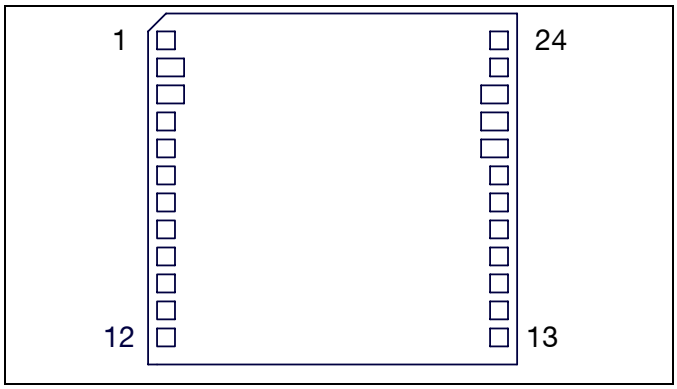
1. $((\frac{1}{0.835}) - 1) \times 24\ W = 4.7\ W$

2. 4.7 W × 5.2°C/W = 24.4°C

3. 110 °C – 24.4°C = max ambient temperature is 85.6°C

The actual temperature will be dependent on several factors such as the PCB size, number of layers and direction of airflow.

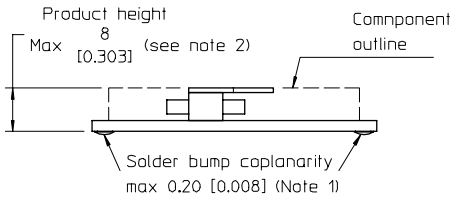
Connections

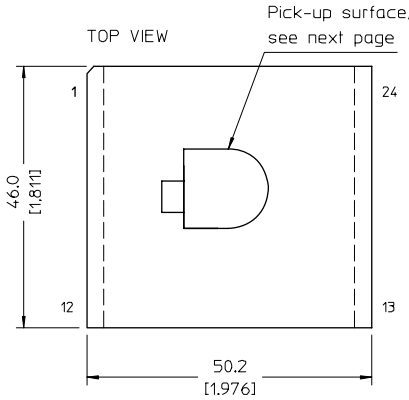


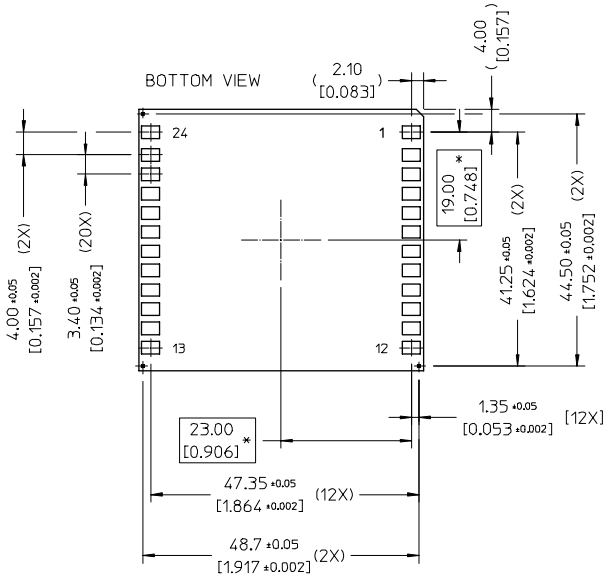
Pin	Designation	Function
2	+ In	Positive input
3	- In	Negative input
5	RC	Remote control pin
6	RC logic	Select pin for neg/pos RC[1)]
15	+ Sense	Positive remote sense
16	Vadj	Output voltage adjust
17	- Sense	Negative remote sense
18-20	- Out	Negative output
21-23	+ Out	Positive output
1,4,7-14,24	NC	Not connected

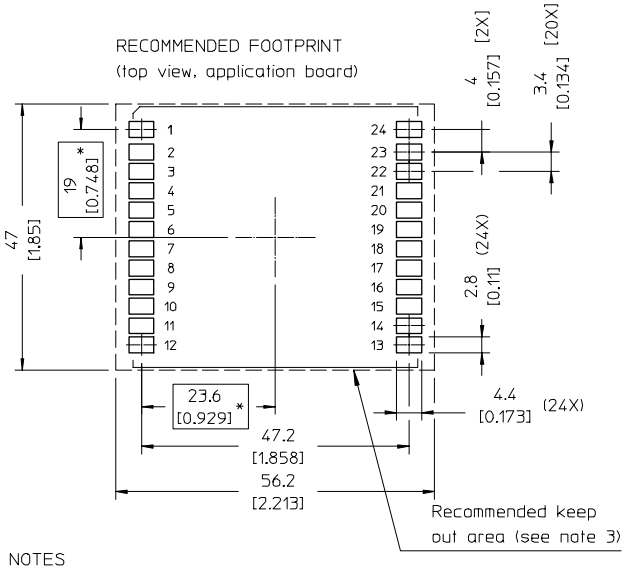
1) Connect – In for negative logic or leave open for positive logic on RC pin.

Mechanical Information









For details on bottom side solder bump and fiducials, see next page.
Bump to bump and fiducial to bump tolerances are not cumulative.

Mounting options

Suffix	Description
S	Surface mounting, type SnAgCu solder
SPB	Surface mounting, type SnPb solder

NOTES

1. The solder bumps are designed to allow coplanarity compensation by melting of the solder bumps between the product and the host board.
   The coplanarity corresponds to the requirements for BGA low melt solder balls (Jedec Publication 95, Design Guide 4.14 revision E, september 2005)

2. Max product height is measured from bottom side of the product PCB but excluding the solder bump (reduced to solder joint thickness after assembly)

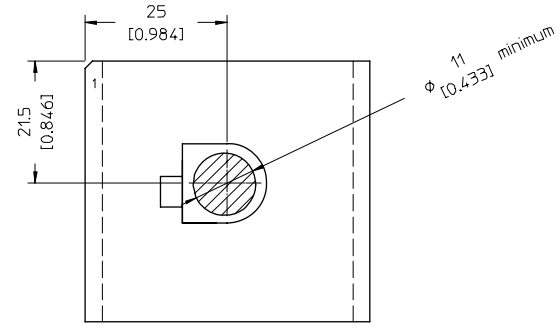
3. Absolute keep out area = 47 x 51.2 is based on mechanical outline and assembly tolerances. The recommended keep out area is at least +3 mm on each connector side to facilitate repair (removal and re-mounting) with a hot air nozzle.

* Boxed dimensions: theoretical distances from product center (center of physical outline)

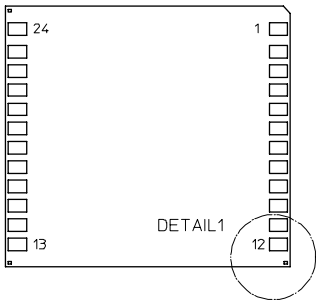
Weight: maximum 25 g
All dimensions in mm [inch].
Tolerances unless specified:
x.x mm ±0.26 [0.01], x.xx mm ±0.13 [0.005]
(not applied on footprint or typical values)

Assembly information

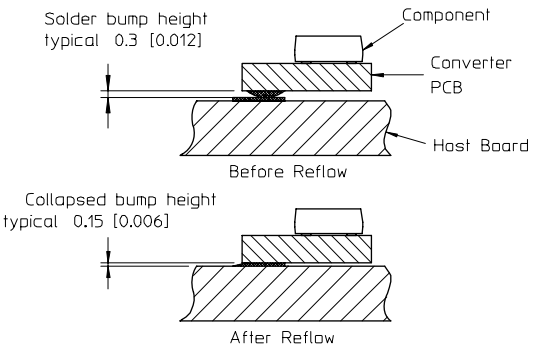
TOP VIEW - pick up surface
on plastic cover,size as
indicated by hatched area

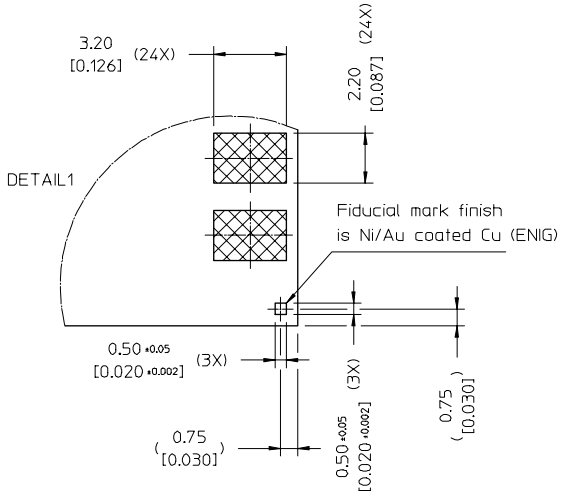


BOTTOM VIEW

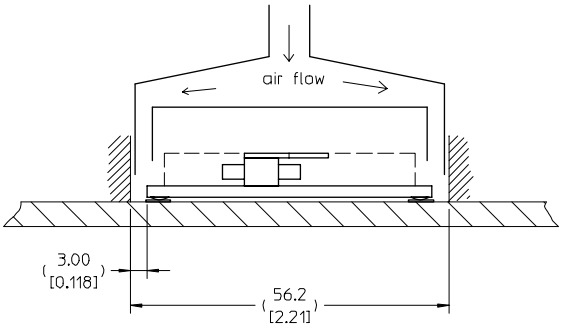


APPLICATION VIEW (detail)





SIDE VIEW - hot air nozzle
Illustration of a recommended design for a hot air
repair nozzle for manual removal and re-mounting



All dimensions in mm [inch].
Tolerances unless specified
x.x mm ±0.26 [0.01], x.xx mm ±0.13 [0.005]
(not applied on footprint or typical values)

Soldering Information - Surface Mounting

The surface mount version of the product is intended for convection reflow or vapor phase reflow in SnPb or Pb-free reflow processes.

Mounting Options

The surface mount version is available in two options, SnPb based or SnAgCu based (Pb-free) solder bumps.

The SnPb solder bumps are intended for SnPb solder paste on the host board and to be reflowed in SnPb reflow process temperatures, typically +210 to +220°C.

The Pb-free solder bumps are intended for Pb-free solder paste on the host board and to be reflowed in Pb-free reflow process temperatures, typically +235 to +250°C.

Note that recommendations for minimum and maximum pin temperature – and maximum peak product temperature – are different depending on mounting option, reflow process type and if the dry packing of the products has been kept intact.

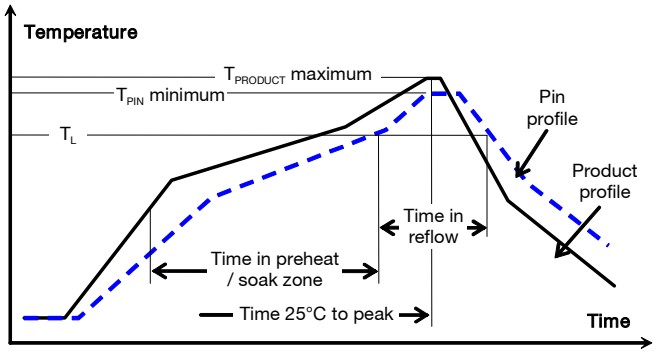
General Reflow Profile Recommendations

The reflow profile should be optimised to avoid excessive heating of the product. It is recommended to have a sufficiently extended preheat time to ensure an even temperature across the host PCB and to minimize the time in reflow.

A no-clean flux is recommended to avoid entrapment of cleaning fluids in cavities inside the product or between the product and the host board, since cleaning residues may affect long time reliability and isolation voltage.

Reflow process specifications[1]		SnPb eutectic	Pb-free
Average ramp-up rate		3°C/s max	3°C/s max
Typical solder melting (liquidus) temperature	T_L	+183°C	+221°C
Minimum reflow time above T_L		30 s	30 s
Minimum pin temperature	T_{PIN}	+210°C	+235°C
Peak product temperature	$T_{PRODUCT}$	+225°C	+260°C
Average ramp-down rate		6°C/s max	6°C/s max
Maximum time 25°C to peak		6 minutes	8 minutes

[1] Note: for mixed SnPb / Pb-free soldering, special recommendations apply

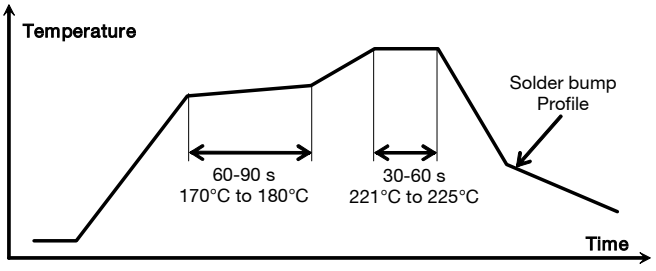


Mixed Solder Process Recommendations

When using products with Pb-free solder bumps and thereby mixing Pb-free solder with SnPb paste on the host board and reflowing at SnPb process temperatures (backwards compatibility), special recommendations apply.

An extended preheat time between +170°C and +180°C for 60 to 90s and a pin reflow temperature (T_{PIN}) between +220°C and +225°C for 30 to 60 s is recommended.

The extended preheat and soak at reflow temperature will minimize temperature gradients and maximize the wetting and solder mixing in the final solder joints. The use of nitrogen reflow atmosphere will further improve the solder joint quality.

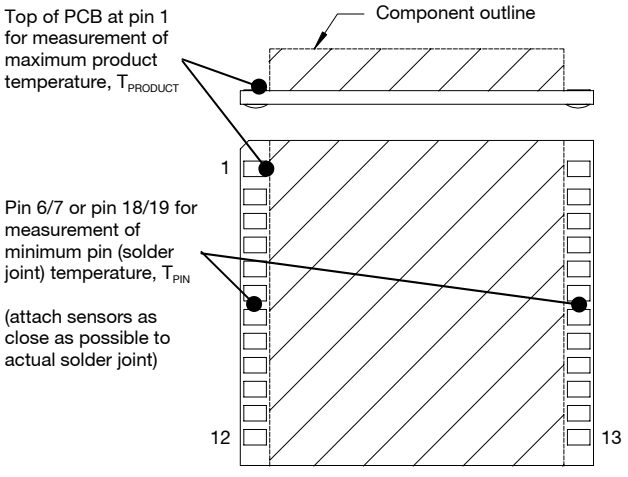


Dry Pack Information

Products intended for Pb-free reflow processes are delivered in standard moisture barrier bags according to IPC/JEDEC standard J-STD-033 (Handling, packing, shipping and use of moisture/reflow sensitivity surface mount devices). The SnPb option of this product is also delivered in dry packing.

Using products in high temperature Pb-free soldering processes requires dry pack storage and handling. In case the products have been stored in an uncontrolled environment and no longer can be considered dry, the modules must be baked according to J-STD-033.

Thermocoupler Attachment



Pin Temperature Recommendations

Pin number 6/7 and 18/19 are chosen as reference locations for the minimum pin (solder joint) temperature recommendations since these will likely be the coolest solder joints during reflow

SnPb Solder Processes

Minimum pin temperature: for SnPb solder processes, a pin temperature (T_{PIN}) in excess of the solder melting temperature, (T_L, +183°C for Sn63Pb37) for more than 30 seconds, and a peak temperature of +210°C is recommended to ensure a reliable solder joint.

A maximum pin temperature of +225°C should be sufficient for most applications but depending on type of solder paste and flux system used on the host board, up to a recommended maximum temperature of +245°C could be used, provided that the products are kept in a controlled environment (dry pack handling and storage) prior to assembly.

Pb-free Solder Processes

For Pb-free solder processes, a pin temperature (T_{PIN}) in excess of the solder melting temperature (T_L, +217 to +221 °C for SnAgCu solder alloys) for more than 30 seconds, and a peak temperature of +235°C on all solder joints is recommended to ensure a reliable solder joint.

Maximum Product Temperature Requirements

Top of the product PCB near pin 1 is chosen as reference location for the maximum (peak) allowed product temperature ($T_{PRODUCT}$), since this will likely be the warmest part of the product during the reflow process.

SnPb Solder Processes

For conventional SnPb solder processes, the product is qualified for MSL 1 according to IPC/JEDEC standard J-STD-020C (no dry pack handling or controlled environment required)

During reflow, $T_{PRODUCT}$ must not exceed +225 °C at any time.

If the products are handled as MSL 3 products, they can withstand up to +260°C as in Pb-free solder processes.

Pb-free Solder Processes

For Pb-free solder processes, the product is qualified for MSL 3 according to IPC/JEDEC standard J-STD-020C.

During reflow, $T_{PRODUCT}$ must not exceed +260 °C at any time.

Surface Mount Assembly and Repair

The solder bumps of the product require particular care during assembly since the solder bumps are hidden between the host board and the product's PCB. Special procedures are required for successful rework of these products.

Assembly

Automatic pick and place equipment should be used to mount the product on the host board. The use of a vision system, utilizing the fiducials on the bottom side of the product, will ensure adequate accuracy. Manual mounting of solder bump products is not recommended.

Note that the actual position of the pick up surface may vary between variants within the product program and is not necessarily in the center of the product outline.

If necessary, it is recommended to fine tune the solder print aperture size to optimize the amount of deposited solder with consideration to screen thickness and solder print capability.

Repair

For a successful repair (removal and replacement) of a solder bump product, a dedicated rework system should be used. The rework system should preferably utilize a bottom side heater and a dedicated hot air nozzle to heat the solder bumps to reflow temperature.

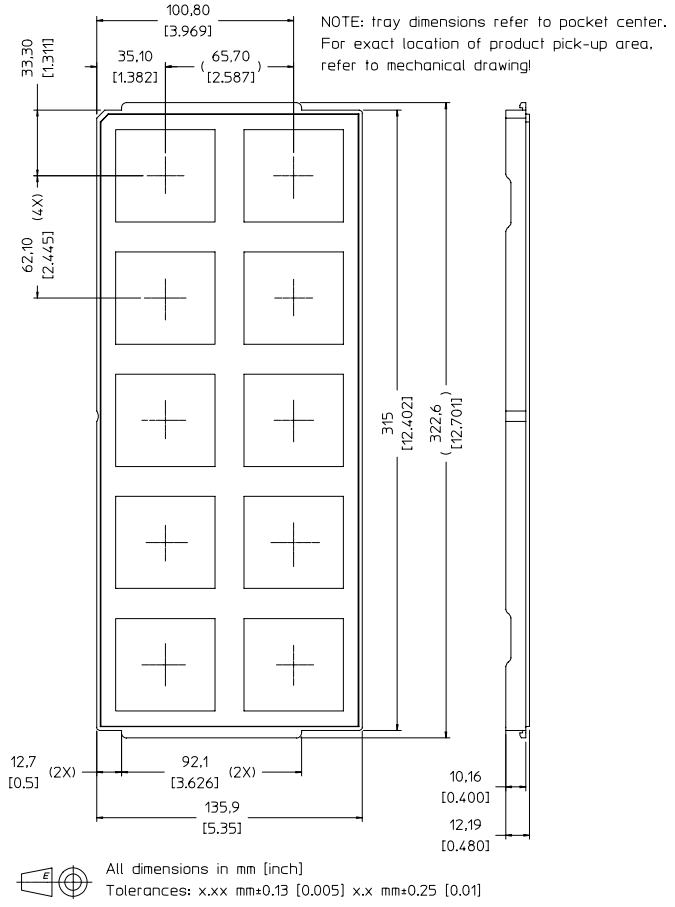
The product is an open frame design with a pick up surface on a large central component. This pick up surface can not be used for removal with a vacuum nozzle since the component solder joints may have melted during the removal reflow.

In order not to damage the product and nearby components during removal and replacement with a new product, it is recommended to use a double wall design of the hot air nozzle to direct the air flow only to the edges of the product, see 'Assembly Information' in the mechanical drawing.

Delivery Package Information

The surface mount version of the product is delivered in antistatic injection molded trays (Jedec design guide 4.10D standard).

Tray Specifications	
Material	Antistatic PPE
Surface resistance	10^5 < Ohm/square < 10^{12}
Baking	The trays can be baked at maximum 125°C for maximum 48 hours
Tray capacity	10 products / tray
Tray thickness	12.19 mm [0.480 inch]
Box capacity	100 products (10 full trays/box)
Tray weight	115 g empty, 330 g full



Product Qualification Specification

Characteristics			
External visual inspection	IPC-A-610		
Change of temperature (Temperature cycling)	IEC 60068-2-14 Na	Temperature range Number of cycles Dwell/transfer time	-40 to +100°C 1000 15 min/0-1 min
Cold (in operation)	IEC 60068-2-1 Ad	Temperature T_A Duration	-45°C 72 h
Damp heat	IEC 60068-2-67 Cy	Temperature Humidity Duration	+85°C 85 % RH 1000 hours
Dry heat	IEC 60068-2-2 Bd	Temperature Duration	+125°C 1000 h
Electrostatic discharge susceptibility	IEC 61340-3-1, JESD 22-A114 IEC 61340-3-2, JESD 22-A115	Human body model (HBM) Machine Model (MM)	Class 2, 2000 V Class 3, 200 V
Immersion in cleaning solvents	IEC 60068-2-45 XA Method 2	Water Glycol ether Isopropanol	+55°C +35°C +35°C
Mechanical shock	IEC 60068-2-27 Ea	Peak acceleration Duration	100 g 6 ms
Moisture reflow sensitivity [1]	J-STD-020C	level 1 (SnPb-eutectic) level 3 (Pb Free)	225°C 260°C
Operational life test	MIL-STD-202G method 108A	Duration	1000 h
Resistance to soldering heat [2]	IEC 60068-2-20 Tb Method 1A	Solder temperature Duration	270°C 10-13 s
Robustness of terminations	IEC 60068-2-21 Test Ua1 IEC 60068-2-21 Test Ue1	Through hole mount products Surface mount products	All leads All leads
Solderability	IEC 60068-2-58 test Td [1] IEC 60068-2-20 test Ta [2]	Preconditioning Temperature, SnPb Eutectic Temperature, Pb-free Preconditioning Temperature, SnPb Eutectic Temperature, Pb-free	150°C dry bake 16 h 215°C 235°C Steam ageing 235°C 245°C
Vibration, broad band random	IEC 60068-2-64 Fh, method 1	Frequency Spectral density Duration	10 to 500 Hz 0.07 g^2/Hz 10 min in each perpendicular direction

Note 1: Only for products intended for reflow soldering (surface mount products)
Note 2: Only for products intended for wave soldering (hole mounted products)